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## TABLE OF CONTENTS

Preface & Acknowledgements	xvii
I. Introduction to precision manufacturing	1
1.1 Precision engineering	1
1.2 Precision manufacturing	2
1.3 Competitive drivers of precision manufacturing	7
1.4 Historical developments in manufacturing	9
1.4.1 Background	9
1.4.2 Key drivers	13
1.4.3 Historical examples	16
1.5 Organization of this book	33
II. Machine design for precision manufacturing	37
2.1 Background on machine design for manufacturing	37
2.2 Philosophy of precision machine design	39
2.3 Sources of error - overview	41
III. Principles of measurement	49
3.1 Definition of terms – accuracy, repeatability, and resolution	49
3.1.1 Accuracy	49
3.1.2 Repeatability (or precision)	53
3.1.3 Resolution	54
3.1.4 Probabilistic measure of accuracy	55
3.2 Metrology and measurement	57

3.3 Abbé's principle	64
3.4 Metrology techniques	67
3.4.1 Measurement of dimension and angle	67
3.4.2 Measurement of form	73
3.4.2.1 Straightness	73
3.4.2.2 Flatness	84
3.4.2.3 Roundness	88
3.4.2.4 Other form errors	99
3.4.3 Measurement of surface roughness	99
3.4.4 Kinematic precision	110
3.5 Subsurface damage	112
IV. Mechanical errors	121
4.1 Introduction	121
4.2 Errors due to machine elements (excluding bearings)	123
4.3 Kinematic design	128
4.3.1 Connectivity	128
4.3.2 Kinematic elements	129
4.3.3 Contact and complex support	133
4.3.4 Summary of kinematic design	142
4.4 Structural compliance	143
4.4.1 Microscale compliance	143
4.4.2 Macroscale compliance	145
4.5 Bearings and spindles	153
4.5.1 Bearings	153
4.5.2 Aerostatic bearings and spindles	163
V. Thermal errors	167
5.1 Background on the thermal error problem	167
5.2 Thermal effects in precision engineering	171
5.3 Determining the effect of temperature other than 20°C	180
5.3.1 Free and constrained bodies	181
5.3.2 Effect of spatial temperature gradients	184
5.3.3 Effect of temperature transients: soak-out time and sinusoidal response	187

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5.4 Conductive, convective, and radiative heat transfer parameters	193
5.5 Specific heat sources and examples of thermal problems	196
5.6 Environmental control of precision machinery	202
5.6.1 Machine enclosures	203
5.6.2 Factory and room enclosures	204
5.6.3 Machine treatment without enclosures	206
5.7 Thermal effects and metrology	208
5.8 Observations	215
VI. Error mapping and error budgets	217
6.1 Introduction	217
6.2 Error mapping	218
6.3 Error budget	232
6.3.1 Definition of error budget	232
6.3.2 Error budget flow chart	233
6.3.3 Combinational rules for errors	234
VII. Error due to compliance and vibration	239
7.1 Introduction	239
7.2 Excitations in machine tools	243
7.3 Weight deformation	246
7.4 Cutting force deformation	249
7.4.1 Type A deformation: Deformation due to the variation of the cutting force	250
7.4.1.1 Introduction and background	250
7.4.1.2 Examples for single edge cutting	254
7.4.1.3 Machine stiffness and directional orientation	256
7.4.2 Type B deformation: Deformation due to the variation of the stiffness along the tool path	263
7.4.3 Comparison of the errors from deformation types A and B	267
7.5 Forced vibrations	272
7.6 Self-excited vibrations (chatter)	273
7.6.1 Introduction	273
7.6.2 Basic stability; effect of structural dynamics	278

7.6.3 Variation of spindle speed and stability lobes	288
7.7 Advanced analysis	292
VIII. Sensors for precision manufacturing	295
8.1 Introduction	295
8.1.1 The relevance of precision manufacturing and the need for in-process monitoring and control	295
8.1.2 Requirements for sensor technology for precision manufacturing	297
8.2 Overview of sensors in manufacturing	300
8.2.1 Introduction	300
8.2.2 Sensor systems for process monitoring	303
8.3 New developments in signal and information processing for tool condition monitoring	308
8.3.1 Introduction	308
8.3.2 Intelligent sensors	311
8.3.3 Implementation strategies	314
8.3.4 Multisensor approaches	316
8.3.5 Sensors for high speed machining	317
8.4 Acoustic emission in manufacturing	320
8.4.1 Background	320
8.4.2 Acoustic emission sources-diagnostics	322
8.4.3 Acoustic emission sources-process monitoring	323
8.4.4 Acoustic emission in machining	325
8.5 Signal processing, feature extraction and sensor fusion	334
8.5.1 Introduction	334
8.5.2 Intelligent sensor defined	337
8.5.3 Sensor fusion defined	338
8.5.4 Fusion methodologies	339
8.5.5 Neural networks	341
8.6 Applications of signal processing and sensor fusion	349
8.6.1 Introduction	349
8.6.2 Tool wear detection using time series analysis of acoustic emission	350

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8.6.2.1	Time series analysis	351
8.6.2.2	Experimental evaluation	355
8.7	Sensor integration using neural networks for intelligent tool condition monitoring	358
8.7.1	Use of multiple sensors	360
8.7.2	Experimental evaluation	363
8.8.	The need for engineering models to design and predict the performance of in-process sensors	369
8.9	Basic sensor classification and new sensing technologies	372
8.9.1	Introduction	372
8.9.2	Basic sensor types	377
8.9.2.1	Mechanical sensors	377
8.9.2.2	Thermal sensors	380
8.9.2.3	Electrical sensors	382
8.9.2.4	Magnetic sensors	382
8.9.2.5	Radiant sensors	383
8.9.2.6	Chemical sensors	383
8.10	Applications of sensors in precision manufacturing	384
8.10.1	AE-based monitoring of grinding wheel dressing	384
8.10.1.1	Fast AE RMS analysis for wheel condition monitoring	385
8.10.1.2	Grinding wheel topographical mapping	387
8.10.1.3	Wheel wear mechanism	389
8.10.1.4	AE-based monitoring of face milling	390
8.10.2	AE-based monitoring of chemical mechanical planarization	393
8.10.2.1	Monitoring of abrasive process parameters	395
8.10.2.2	Precision scribing of CMP-treated wafers	398
8.10.2.3	AE-based endpoint detection for CMP	401
8.10.2.4	AE monitoring of surface chemical reactions for copper CMP	403

8.10.2.5 AE characteristics of oxidation and dissolution in copper CMP	411
8.10.2.6 Monitoring of precision scribing	416
8.10.2.7 Monitoring of ultraprecision Turning of Single crystal copper	418
8.10.2.8 Monitoring of ultraprecision turning of polycrystalline copper	421
8.11 Summary	422
IX.    Process planning for precision manufacturing	425
9.1 Manufacturing system characteristics	425
9.2 Process planning basics	435
9.3 Process capability	438
9.3.1 Background	438
9.3.2 Process capability defined	440
9.4 $C_p$ as a planning metric	444
9.5 Legacy-system integration for precision manufacturing	451
9.6 Future integration for precision manufacturing process planning	452
X.     Precision machining processes	455
10.1 Introduction	455
10.2 Influence of machining parameters, work material, and tool geometry	462
10.2.1 Influence of uncut chip thickness	462
10.2.2 Machining brittle materials	465
10.2.3 Effects of work material crystallography/ directionality	472
10.3 Process operating conditions	478
10.4 Precision mfg. processes-diamond turning/milling	482
10.4.1 Introduction	482
10.4.2 Machine tool design	484
10.4.3 Tool design and alignment	491
10.4.4 Chip formation and process mechanics	496
10.5 Abrasive processes – fixed and loose	505
10.5.1 Fixed abrasive processes	505

10.5.1.1	Material removal mechanisms	505
10.5.1.2	Grinding forces, power and specific energy	512
10.5.1.3	Grinding stiffness, contact stiffness and process time constant	517
10.5.1.4	Nanogrinding	520
10.5.2	Loose abrasive processes	521
10.5.2.1	Polishing and lapping	522
10.5.2.2	Chemical mechanical planarization (CMP)	532
10.5.2.3	Process modeling in CMP	540
10.6	Non-traditional processes	551
XI.	Precision manufacturing applications and challenges	555
11.1	Introduction	555
11.2	Basic semiconductor device manufacturing	559
11.2.1	Introduction	559
11.2.2	So, what are they anyway and how are they made?	561
11.2.2.1	Microfabrication: background and overview	561
11.2.2.2	Lithography	564
11.3	Applications of semiconductor manufacturing – MEMS	570
11.4	Nanotechnology	572
11.4.1	Background and definitions	572
11.4.2	Nanostructured materials	576
11.4.3	Nanofabrication techniques	578
11.4.3.1	E-beam and nano-imprint Fabrication	582
11.4.3.2	Epitaxy and strain engineering	585
11.4.3.2.1	Quantum structure nanofabrication using epitaxy on patterned substrates	585
11.4.3.2.2	Quantum structure nanofabrication using strain-induced self-assembly	587

11.4.3.3 Scanned probe techniques	589
11.4.4 Self-assembly	595
11.5 MEMS and nanotechnology applications	600
11.5.1 Nanotechnology applications	601
11.6 Micro-machining and small scale defects	604
11.6.1 Introduction	604
11.6.2 Surface and edge finish	607
11.6.3 Modeling	611
11.6.3.1 Finite element modeling	613
11.6.3.2 Molecular dynamics	615
11.6.3.3 Multiscale modeling	619
11.6.3.4 Mechanistic modeling	620
11.6.4 Workpiece and design issues	622
11.6.4.1 Micromolding	622
11.6.4.2 Creation of micropattern and microstructure	625
11.6.4.3 Creation of 3-dimensional shapes	630
11.6.4.4 Ultrasonic vibration assisted micromachining	631
11.6.5 Micro-tools	633
11.6.6 Cutting fluid	638
11.6.7 Metrology in micromachining	640
11.6.8 Conclusion and outlook	644
11.7 Burrs – preventing and minimizing burr formation in precision components	646
11.7.1 Introduction and background	647
11.7.2 Process-based solutions	651
11.7.2.1 Milling	652
11.7.2.2 Drilling	654
11.7.3 Examples of application of burr minimization strategies	657
11.7.3.1 Tool path planning in milling	657
11.7.3.2 Burr control chart	660
11.7.3.3 Integrated process planning and burr minimization	661
11.7.4 Summary and conclusions	662

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XII. Future of precision manufacturing	665
12.1 Introduction	665
12.2 The manufacturing pipeline	666
12.3 Sustainable design/environmentally conscious design and manufacturing	669
12.3.1 Technologies for sustainable manufacturing	670
12.3.2 Green manufacturing pipeline	671
12.3.3 Sustainable manufacturing or “does green = sustainable?”	676
12.3.4 Manufacturing technology wedges	678
12.3.5 Examples of wedge technology application areas for manufacturing	680
12.3.5.1 Consumable use in machining	681
12.3.5.2 Energy use in nanoscale manufacturing	685
12.4 Environmentally conscious design of precision machines	693
12.4.1 Sustainability budgets	694
12.4.2 Constructing the sustainability budget	696
12.5 Summary comments/conclusion	701
References	705
Index	765





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